	A F Diode	Product Line of s Incorporated	P	PERICOM®	
SPECIFICA7	TON	FOR	A	PPROVAL	
CUSTOMER					
NOMINAL FREQUENCY		24.576000 MHz			
PRODUCT TYPE	TYF	PE FL 3.2x2	.5 SE	AM SEALED CRYSTA	
SPEC. NO. ( P/N )		FL2450062Q			
CUSTOMER P/N					
ISSUE DATE		September 21, 2017			
VERSION		Α			
APPROVED	PRI	EPARED		QA	
Brenda	C	laire		Dong Yang	
Diodes Incorporation No.2, Ziqiang 5th Rd., Zhongli Induz Zhongli Dist., Taoyuan City 32063, TEL: 886-3-451-8888 FAX: 886-3-461-3865 http://www.diodes.com		C.) *  *  *	HF-Ha REAC	e Compliant alogen Free H Compliant Q200 Compliant	

# TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL

### FL2450062Q

VER. A 21-Sep-17

## **VERSION HISTORY**

Version No.	Version Date	Customer Receipt Date	Supplier Receipt Date	Description	Notes
A	Sep.21,2012			Initial Release	



# **TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL**

### FL2450062Q

VER. A 21-Sep-17

#### **ELECTRICAL SPECIFICATIONS**

ltem	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	24.576000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	14	pF	
Calibration Tolerance	FL	±10	ppm	at 25°C±3°C
Operating Temperature Range	TR	-40 to +85	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	±40	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		300	μW	
Equivalent Series Resistance	ESR	35	Ω	Мах
Shunt Capacitance	C0	2	pF	Мах
Aging at 25°C		±3	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	MΩ	Min

\* This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).

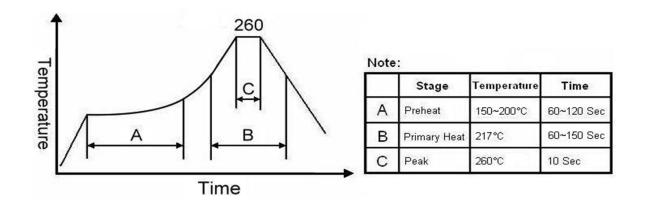


## **TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL**

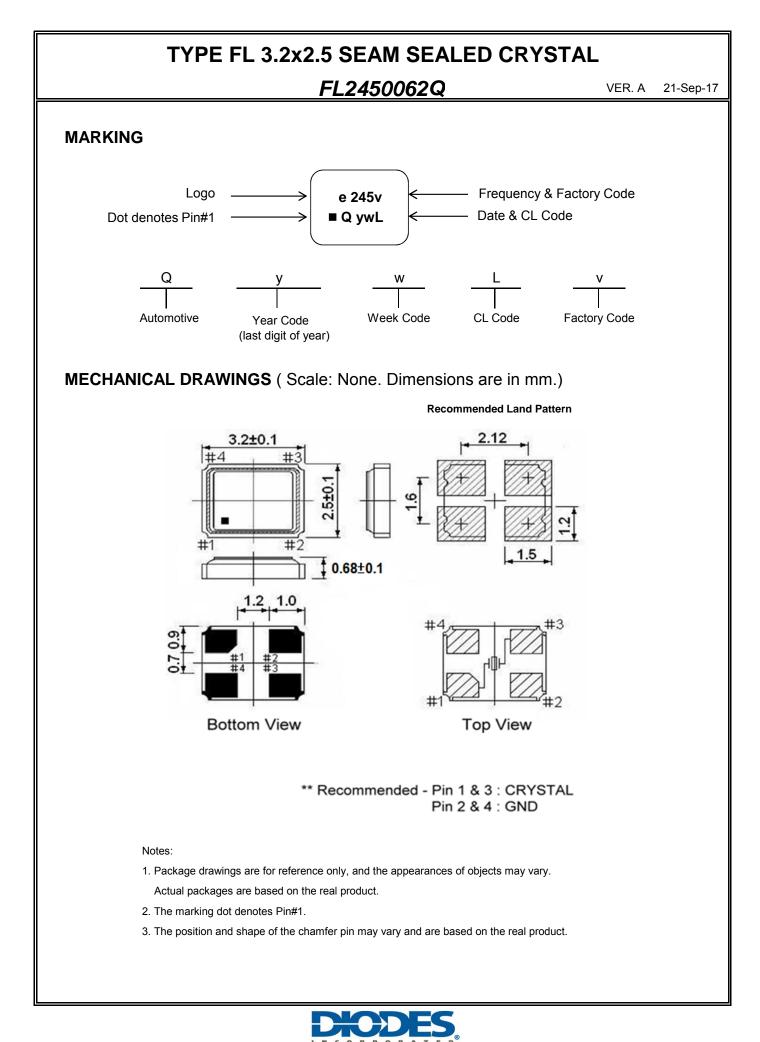
### FL2450062Q

# **AEC-Q200 RELIABILITY TEST SPECIFICATIONS:** 1. Initial 1.1 Physical Dimensions: JESD22, Method JB1-100 1.2 External Visual: MIL-STD-883, Method 2009 1.3 Freq. Vs. Temperature: Per Specification/Datasheet 2. Mechanical 2.1 Mechanical Shock: MIL-STD-202 Method 213 2.2 Vibration: MIL-STD-202 Method 204 2.3 Solderability: J-STD-002 2.4 Board Flex: AEC Q200-005 2.5 Terminal Strength (SMD): AEC Q200-006 3.Environmental 3.1 Temp Cycle: JESD22, Method JA-104 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210 3.3 High Temperature Operating Life: MIL-STD-202, Method 108 3.4 High Temp Exposure: MIL-STD-202, Method 108 3.5 High Temp & High Humidity: MIL-STD-202, Method 103 3.6 Thermal Shock: MIL-STD-202, Method 107 SUGGESTED IR REFLOW PROFILE

\*As per IPC-JEDEC J-STD-020D









# **TYPE FL 3.2x2.5 SEAM SEALED CRYSTAL** FL2450062Q VER. A 21-Sep-17 Tape & Reel Index Mark 2.0 0.25±0.05 Ø1.55 Ø1.0 4.0 1.75 R0.3 $\oplus$ (MAX. 3.5±0.05 8±0.2 3.4 53 2.7 Feeding 8.0 1.4 Ø60.2±0.5 78-8 9.0±0.3

1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.

12±1.4

2. 160mm minimum trailer of empty carrier tape sealed with cover tape.



